(SOLE INVENTOR)
IBM Docket No.: FI920030315US1

Declaration and Power of Attorney for Patent Application

As below named inventor, I hereby declare that:

the specification of which (check one)

Application Number

My residence, post office address and citizenship are as stated below next to my name; I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

OVERLAP STACKING OF CENTER BUS BONDED MEMORY CHIPS FOR DOUBLE DENSITY AND METHOD OF MANUFACTURING THE SAME

x	is attached hereto. was filed on	_ as Application Serial No	and was amended on			
I hereby state that I have reviewed and understand the contents of the above-identified specification including the claims, as amended by amendment referred to above.						
I acknowledge t §1.56.	he duty to disclose info	rmation which is material to th	e patentability as defined in 37 CFF			
patent or invente country other th foreign applicati	or's certificate, or §365(a an the United States, list	n) of any PCT International appli red below and have also identifi or's certificate, or PCT Internation	55(b) of any foreign application(s) for ication which designated at least one ied below, by checking the box, any onal application having a filing date			
Prior Fo Number	reign Application(s): Country	Day/Month/Year	Priority Claimed			
I hereby claim th	ne benefit under 35 USC	§119(e) of any United States pro	ovisional application(s) listed below:			

Filing Date

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I hereby claim the benefit under 35 USC §120 of any United States application(s), or §365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 USC §112, I acknowledge the duty to disclose information material to the patentability of this application as defined in 37 CFR §1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

Prior	U.S.	Appli	icati	ons:
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Serial No.

Filing Date

Status (patented, pending, abandoned)

I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Anthony P. DeLio (Reg. No. 18,729); Peter W. Peterson (Reg. No. 31,867); John J. Tomaszewski (Reg. No. 26,241); Robert Curcio (Reg. No. 44, 638); Kelly M. Reynolds (47,898); Joseph P. Abate (Reg. No. 30,238); Jay H. Anderson (Reg. No. 38,371); Mark Bilak, 47423: Ira D. Blecker (Reg. No. 29,894); Steven Capella (Reg. No. 33,086); James J. Cioffi (Reg. No. 51,564); Harold Huberfield (Reg. No. 26,665); Todd M.C. Li (Reg. No. 45,554); Anthony N. Magistrale (Reg. No. 35,595); Margaret A. Pepper (Reg. No. 45,008); H. Daniel Schnurmann (Reg. No. 35,791); Eugene I. Shkurko (Reg. No. 36,678); Steven Soucar (Reg. No. 32,440); Tiffany L. Townsend (Reg. No. 43,199); Christopher A. Hughes, (Reg. No. 26,914); Edward A. Pennington, (Reg. No. 32,588); John E. Hoel, (Reg. No. 26,279); and Joseph C. Redmond, Jr., Reg. No. (18,753).

Address all telephone calls to: Robert Curcio of DeLIO & PETERSON, LLC at (203) 787-0595.

Address all correspondence to: DeLIO & PETERSON, LLC, (Cust. No. 29505)

121 Whitney Avenue New Haven, CT 06510

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(1)	Inventor:	Edmund D. Blackshear
	Signature:	
		Date
	Residence:	295 Cedar Hill Road, Wappingers Falls, New York 12590
	Citizenship:	USA
	Post Office Address:	SAME AS RESIDENCE

ibmf100407000dec

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(1) Inventor:

Edmund DaBlackshear

Signature:

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Citizenship: USA

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Patents of Invention or Design - Thailand

DEED OF ASSIGNMENT

Date

Title of Invention/Design: OVERLAP STACKING OF CENTER BUS BONDED MEMORY CHIPS FOR DOUBLE DENSITY AND METHOD OF MANUFACTURING THE SAME

Assignor(s):

(1) Edmund D. Blackshear

Assignee:

International Business Machines Corporation

Armonk, N.Y. 10504, USA

The Assignor(s) declare that I/we are the inventor(s) of the above-mentioned invention/design and for due consideration hereby assign the right to apply for and obtain patents therefor in Thailand to the Assignee and the Assignee hereby accepts such assignment.

In witness whereof, the Assignor(s) and Assignee have signed their names below, effective on the date above.

ASSIGNORS

Edmund D. Blackshear